

## Laser Applications in Microelectronic and Optoelectronic Manufacturing XV (LA110)

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Conference Chairs: Hiroyuki Niino, National Institute of Advanced Industrial Science and Technology (Japan); Michel Meunier, Ecole Polytechnique de Montréal (Canada); Bo Gu, IPG Photonics Corp. (United States); Guido Hennig, MDC Max Daetwyler AG (Switzerland)

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#### Honorary Chair: Jan J. Dubowski, Univ. de Sherbrooke (Canada)

Laser processing of materials, once largely curiosity driven, is now an established technology for micromachining, thin-film synthesis, device fabrication and even nanoscale synthesis and processing of materials. The main driving force behind these developments is the seemingly limitless adaptability of lasers in providing unique material processing solutions, routes for manufacturing otherwise unattainable devices, and cost-effective solutions to complex manufacturing processes. Laser processing is becoming an established enabling technology for the manufacture of microelectronic, optoelectronic and MEMS devices, with industrial applications emerging at an increasing rate; meanwhile, applications to nanotechnology are also rapidly evolving.

The aim of this conference is to provide a forum for discussion of fundamentals, methods, and techniques in laser materials processing and their relation to the applications and manufacturing of micro- and nanoscale electronic, photonic, optical, mechanical, fluidic, and hybrid devices. As in previous years, we expect to offer awards for the best student poster and student oral presentations.

Papers are solicited on, but not limited to, the following topics within the broad area of microelectronics and optoelectronics manufacturing:

- fundamental aspects of laser-surface interaction, including desorption and ablation
- laser modification of materials (annealing, doping, intermixing, photosensitivity)
- laser cleaning, texturing, bending and repair
- laser microengineering and nanoengineering of materials
- pulsed-laser deposition, laser-assisted thin-film epitaxy, atomic-layer epitaxy
- laser pattern transfer, laser-induced forward transfer, and other rapid prototyping and direct-write technologies
- laser processing from cw to fs time scales
- laser processing across wavelength scales from VUV to IR
- laser manufacture of MEMS and microsystems, including microfluidic chips
- laser microprocessing of electronic and optoelectronic materials for advanced devices and integrated systems
- Laser Processing in Microelectronic and Optoelectronic Manufacturing
- diagnostics for laser produced plasmas, including real-time monitoring techniques
- generation and dynamics of laser ablation plumes, including gas-dynamic effects, charge generation and charge transfer
- modeling of laser-materials and laser-plume interactions for quantitative prediction of process parameters
- novel laser systems and optics for materials processing and device fabrication
- resonant infrared pulsed-laser deposition
- laser-induced modification of glasses for applications in optoelectronic and fluidic micro-devices.

#### JOINT SESSION WITH LA113

We are proud to co-sponsor a joint session on ultrafast laser micromachining with Biomedical and other Applications of Ultrafast Lasers X (LA113). This session will address important emerging technologies at the femtosecond time scale, for a broad audience of researchers in the fields of ultra-fast lasers and laser processing, together with experts at the forefront of alternative micro- and nanofabrication technologies. The topics will cover, but will not be limited to, ultra-fast laser sources, fundamentals of ultra-fast lasermatter interaction, and novel machining techniques.

#### SPECIAL SESSION: The LAMOM 15th Year Anniversary Session

In 1995, a conference 'Laser-Induced Thin Film Processing' was coorganized and chaired by **Jan J. Dubowski** at Photonics West in San Jose (February 8-10, 1995). This meeting was the beginning of a series known at Photonics West as LAMOM (Laser Applications in Microelectronic and Optoelectronic Manufacturing). 15 years later, we plan to have a special session in frame of LAMOM-XV, with many researchers who, in those days, were shaping the laser related materials research and manufacturing with lasers. Early LAMOMs were dominated largely by pulsed laser deposition papers, but we've moved since towards surface processing, femtosecond lasers, fiber lasers, nanotechnologies.

Preliminary list of invited speakers to this special session:

- 1. R. Haglund 'Pulsed laser deposition: 15 years later'
- 2. J. Mazumder 'Laser manufacturing of durable goods: a 15-year perspective'
- 3. D. Chrisey 'Pulsed Laser deposition in device research and manufacturing'
- 4. I. Boyd 'Excimer ultraviolet sources for thin film deposition: a 15 year perspective'

5. H. Helvajian 'Low-fluence laser interaction with materials: research and applications shaped by tools advancement'

## Abstract Due Date: 13 July 2009 Manuscript Due Date: 21 December 2009

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